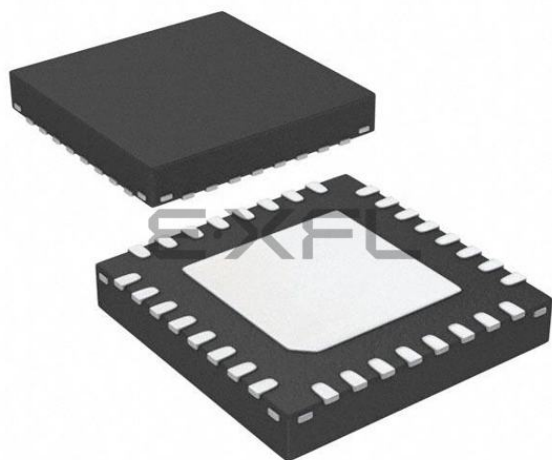




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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	28
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VQFN Exposed Pad
Supplier Device Package	32-HVQFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc1114fhn33-203-5

- LPC1100L series available as TSSOP28 package, DIP28 package, TSSOP20 package, and SO20 package.
- Extended temperature (–40 °C to +105 °C) for selected parts (see [Table 2](#)).

3. Applications

- eMetering
- Alarm systems
- Lighting
- White goods

4. Ordering information

Table 1. Ordering information

Type number	Package		
	Name	Description	Version
SO20, TSSOP20, TSSOP28, and DIP28 packages			
LPC1110FD20	SO20	SO20: plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
LPC1111FDH20/002	TSSOP20	TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
LPC1112FD20/102	SO20	SO20: plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
LPC1112FDH20/102	TSSOP20	TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
LPC1112FDH28/102	TSSOP28	TSSOP28: plastic thin shrink small outline package; 28 leads; body width 4.4 mm	SOT361-1
LPC1114FDH28/102	TSSOP28	TSSOP28: plastic thin shrink small outline package; 28 leads; body width 4.4 mm	SOT361-1
LPC1114FN28/102	DIP28	DIP28: plastic dual in-line package; 28 leads (600 mil)	SOT117-1
HVQFN24/33, LQFP48, and TFBGA48 packages			
LPC1111FHN33/101	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1111FHN33/102	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1111FHN33/201	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1111FHN33/202	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1111FHN33/103	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1111JHN33/103	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1111FHN33/203	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1111JHN33/203	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1112FHN33/101	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1112FHN33/102	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a

Table 1. Ordering information ...continued

Type number	Package		
	Name	Description	Version
LPC1114FHI33/302	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 5 × 5 × 0.85 mm	n/a
LPC1114FHI33/303	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 5 × 5 × 0.85 mm	n/a
LPC1114JHI33/303	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 5 × 5 × 0.85 mm	n/a
LPC1114FHN33/203	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1114JHN33/203	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1114FHN33/303	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1114JHN33/303	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1114FHN33/333	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1114JHN33/333	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1113FBD48/301	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1113FBD48/302	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1113FBD48/303	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1113JBD48/303	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1114FBD48/301	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1114FBD48/302	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1114FBD48/303	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1114JBD48/303	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1114FBD48/323	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1114JBD48/323	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1114FBD48/333	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1114JBD48/333	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1115FBD48/303	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2

Table 1. Ordering information ...continued

Type number	Package		
	Name	Description	Version
LPC1115JBD48/303	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1115FET48/303	TFBGA48	plastic thin fine-pitch ball grid array package; 48 balls; body 4.5 × 4.5 × 0.7 mm	SOT1155-2
LPC1115JET48/303	TFBGA48	plastic thin fine-pitch ball grid array package; 48 balls; body 4.5 × 4.5 × 0.7 mm	SOT1155-2

4.1 Ordering options

Table 2. Ordering options

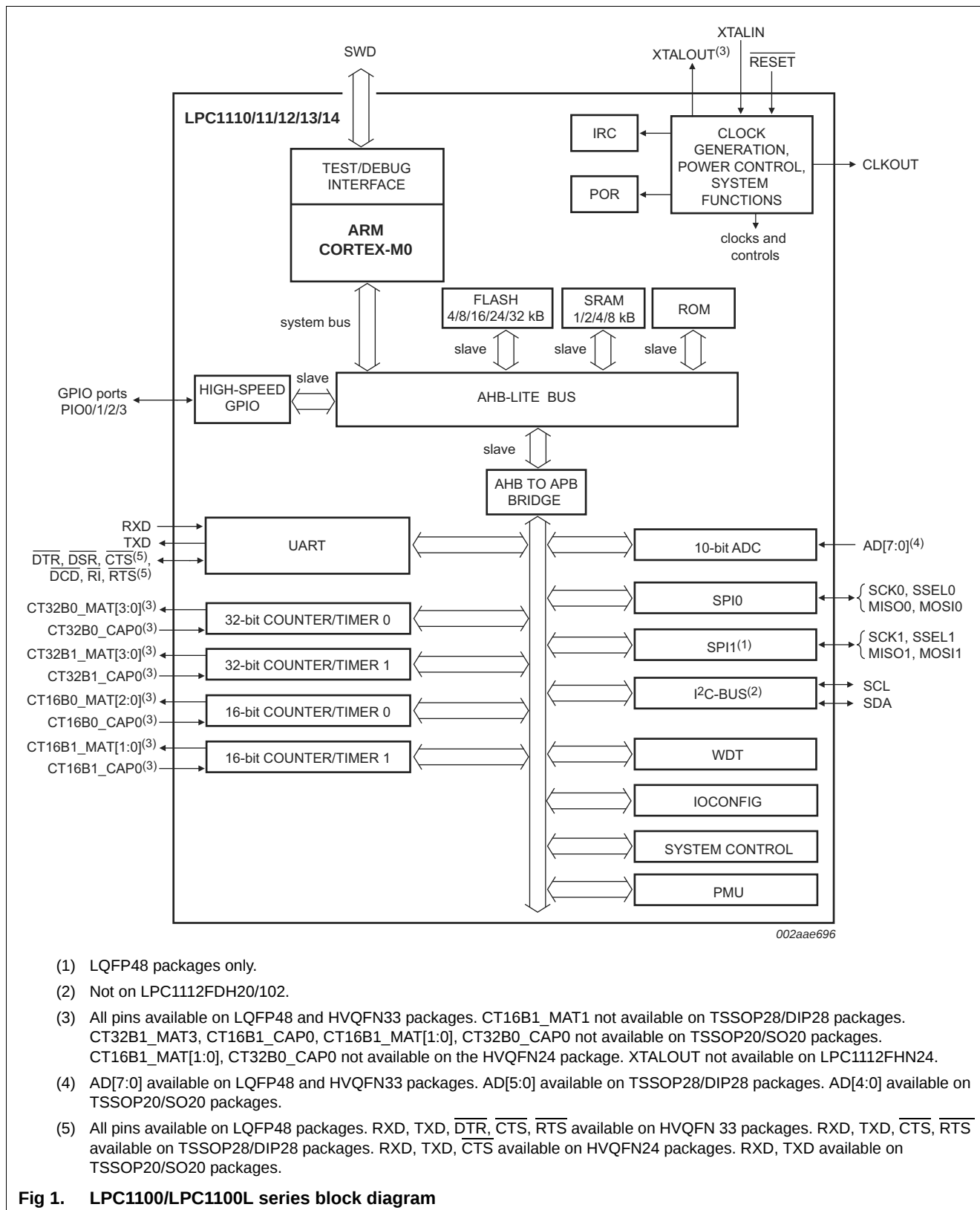
Type number	Series	Flash	Total SRAM	Power profiles	UART	I ² C/ Fast+	SPI	ADC channel	GPIO	Package	Temp ^[1]
LPC1110											
LPC1110FD20	LPC1100L	4 kB	1 kB	yes	1	1	1	5	16	SO20	F
LPC1111											
LPC1111FDH20/002	LPC1100L	8 kB	2 kB	yes	1	1	1	5	16	TSSOP20	F
LPC1111FHN33/101	LPC1100	8 kB	2 kB	no	1	1	1	8	28	HVQFN33	F
LPC1111FHN33/102	LPC1100L	8 kB	2 kB	yes	1	1	1	8	28	HVQFN33	F
LPC1111FHN33/103	LPC1100XL	8 kB	2 kB	yes	1	1	2	8	28	HVQFN33	F
LPC1111JHN33/103	LPC1100XL	8 kB	2 kB	yes	1	1	2	8	28	HVQFN33	J
LPC1111FHN33/201	LPC1100	8 kB	4 kB	no	1	1	1	8	28	HVQFN33	F
LPC1111FHN33/202	LPC1100L	8 kB	4 kB	yes	1	1	1	8	28	HVQFN33	F
LPC1111FHN33/203	LPC1100XL	8 kB	4 kB	yes	1	1	2	8	28	HVQFN33	F
LPC1111JHN33/203	LPC1100XL	8 kB	4 kB	yes	1	1	2	8	28	HVQFN33	J
LPC1112											
LPC1112FD20/102	LPC1100L	16 kB	4 kB	yes	1	1	1	5	16	SO20	F
LPC1112FDH20/102	LPC1100L	16 kB	4 kB	yes	1	-	1	5	14	TSSOP20	F
LPC1112FDH28/102	LPC1100L	16 kB	4 kB	yes	1	1	1	6	22	TSSOP28	F
LPC1112FHN24/202	LPC1100L	16 kB	4 kB	yes	1	1	1	6	19	HVQFN24	F
LPC1112FHN33/101	LPC1100	16 kB	2 kB	no	1	1	1	8	28	HVQFN33	F
LPC1112FHN33/102	LPC1100L	16 kB	2 kB	yes	1	1	1	8	28	HVQFN33	F
LPC1112FHN33/103	LPC1100XL	16 kB	2 kB	yes	1	1	2	8	28	HVQFN33	F
LPC1112JHN33/103	LPC1100XL	16 kB	2 kB	yes	1	1	2	8	28	HVQFN33	J
LPC1112FHN33/201	LPC1100	16 kB	4 kB	no	1	1	1	8	28	HVQFN33	F
LPC1112FHN33/202	LPC1100L	16 kB	4 kB	yes	1	1	1	8	28	HVQFN33	F
LPC1112FHN33/203	LPC1100XL	16 kB	4 kB	yes	1	1	2	8	28	HVQFN33	F
LPC1112JHN33/203	LPC1100XL	16 kB	4 kB	yes	1	1	2	8	28	HVQFN33	J
LPC1112FHI33/102	LPC1100L	16 kB	2 kB	yes	1	1	1	8	28	HVQFN33	F
LPC1112FHI33/202	LPC1100L	16 kB	4 kB	yes	1	1	1	8	28	HVQFN33	F
LPC1112FHI33/203	LPC1100XL	16 kB	4 kB	yes	1	1	2	8	28	HVQFN33	F
LPC1112JHI33/203	LPC1100XL	16 kB	4 kB	yes	1	1	2	8	28	HVQFN33	J

Table 2. Ordering options ...continued

Type number	Series	Flash	Total SRAM	Power profiles	UART	I ² C/ Fast+	SPI	ADC channel	GPIO	Package	Temp ^[1]
LPC1115JBD48/303	LPC1100XL	64 kB	8 kB	yes	1	1	2	8	42	LQFP48	J
LPC1115FET48/303	LPC1100XL	64 kB	8 kB	yes	1	1	2	8	42	TFBGA48	F
LPC1115JET48/303	LPC1100XL	64 kB	8 kB	yes	1	1	2	8	42	TFBGA48	J

[1] F = -40 °C to +85 °C, J = -40 °C to +105 °C.

5. Block diagram



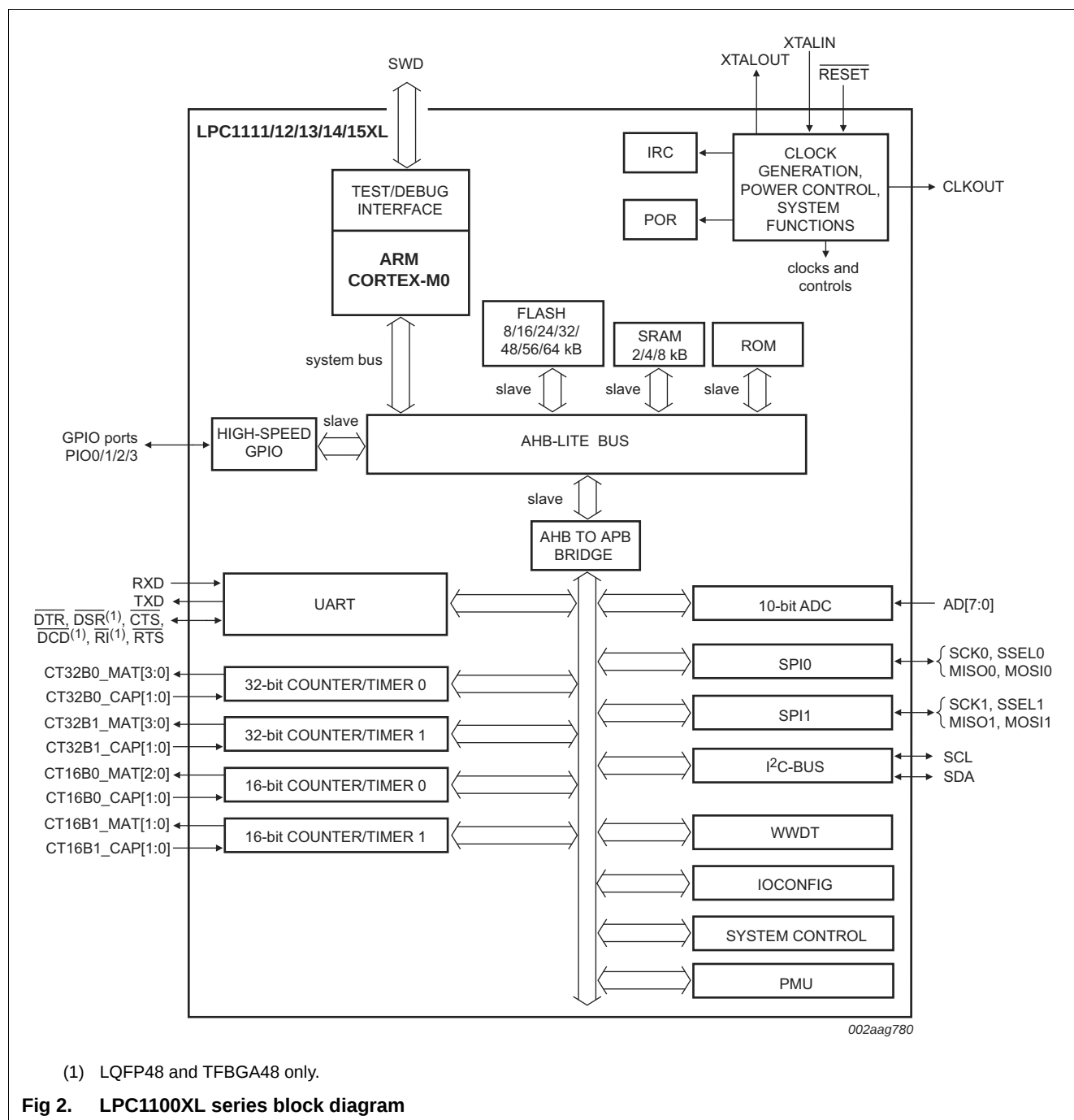


Table 3. Pin description overview

Part	Pin description table	Pinning diagram
LPC1114FHN33/203	Table 11	Figure 7
LPC1114JHN33/203	Table 11	Figure 7
LPC1114FHN33/301	Table 9	Figure 6
LPC1114FHN33/302	Table 9	Figure 6
LPC1114JHN33/303	Table 11	Figure 7
LPC1114FHN33/303	Table 11	Figure 7
LPC1114FHN33/333	Table 11	Figure 7
LPC1114JHN33/333	Table 11	Figure 7
LPC1114FHI33/302	Table 9	Figure 6
LPC1114FHI33/303	Table 11	Figure 7
LPC1114JHI33/303	Table 11	Figure 7
LPC1113FBD48/301	Table 8	Figure 3
LPC1113FBD48/302	Table 8	Figure 3
LPC1113FBD48/303	Table 10	Figure 4
LPC1113JBD48/303	Table 10	Figure 4
LPC1114FBD48/301	Table 8	Figure 3
LPC1114FBD48/302	Table 8	Figure 3
LPC1114FBD48/303	Table 10	Figure 4
LPC1114JBD48/303	Table 10	Figure 4
LPC1114FBD48/323	Table 10	Figure 4
LPC1114JBD48/323	Table 10	Figure 4
LPC1114FBD48/333	Table 10	Figure 4
LPC1114JBD48/333	Table 10	Figure 4
LPC1115FBD48/303	Table 10	Figure 4
LPC1115JBD48/303	Table 10	Figure 4
LPC1115FET48/303	Table 10	Figure 5
LPC1115JET48/303	Table 10	Figure 5

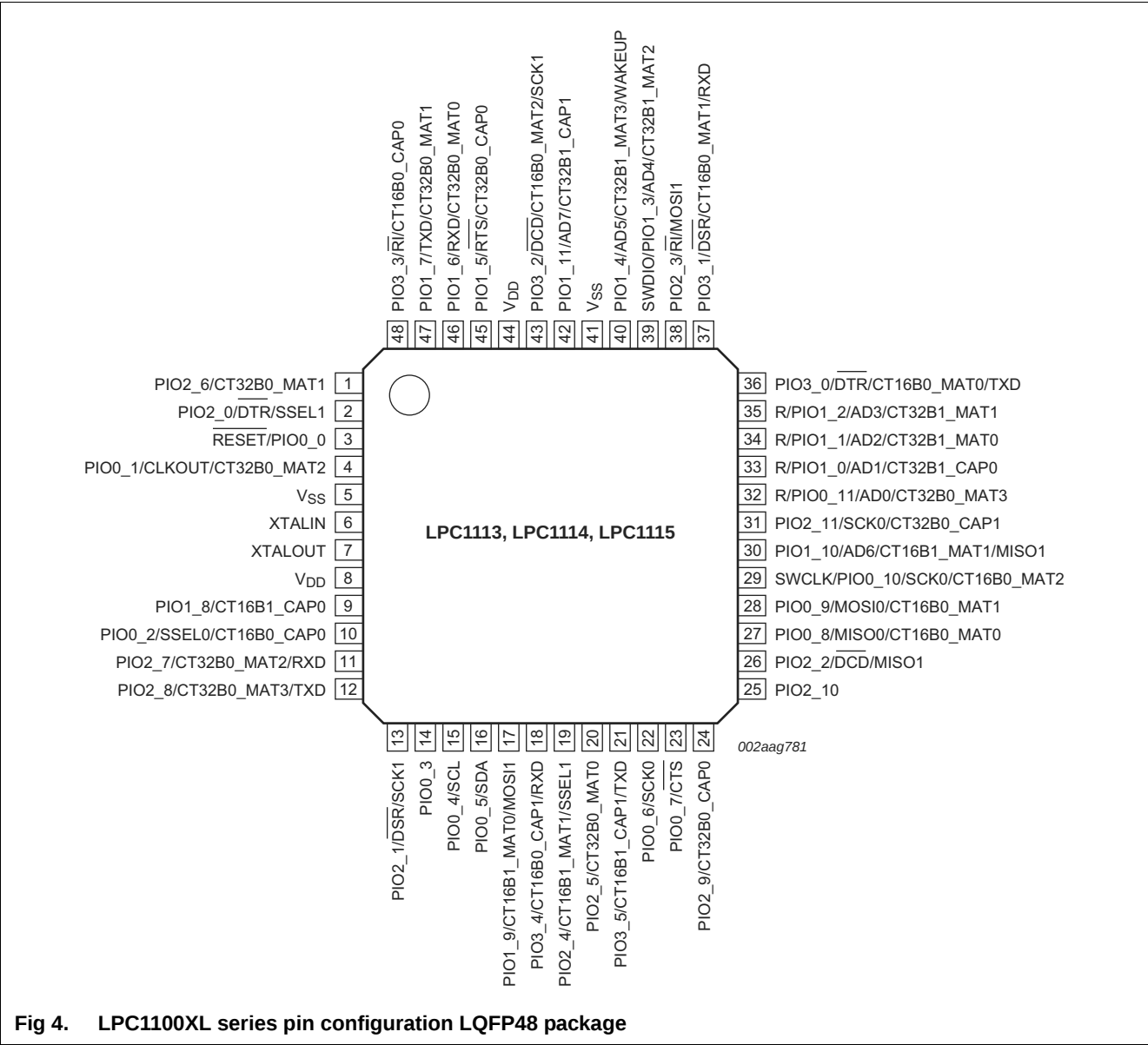


Fig 4. LPC1100XL series pin configuration LQFP48 package

6.2 Pin description

Table 4. LPC1100L series: LPC1110/11/12 pin description table (SO20 and TSSOP20 package with I²C-bus pins)

Symbol	Pin SO20/ TSSOP20	Start logic input	Type	Reset state [1]	Description
PIO0_0 to PIO0_11			I/O		Port 0 — Port 0 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 0 pins depends on the function selected through the IOCONFIG register block.
RESET/PIO0_0	17 [2]	yes	I	I; PU	RESET — External reset input with 20 ns glitch filter. A LOW-going pulse as short as 50 ns on this pin resets the device, causing I/O ports and peripherals to take on their default states, and processor execution to begin at address 0. In deep power-down mode, this pin must be pulled HIGH externally. The RESET pin can be left unconnected or be used as a GPIO pin if an external RESET function is not needed and Deep power-down mode is not used.
			I/O	-	PIO0_0 — General purpose digital input/output pin with 10 ns glitch filter.
PIO0_1/CLKOUT/ CT32B0_MAT2	18 [3]	yes	I/O	I; PU	PIO0_1 — General purpose digital input/output pin. A LOW level on this pin during reset starts the ISP command handler.
			O	-	CLKOUT — Clockout pin.
			O	-	CT32B0_MAT2 — Match output 2 for 32-bit timer 0.
PIO0_2/SSEL0/ CT16B0_CAP0	19 [3]	yes	I/O	I; PU	PIO0_2 — General purpose digital input/output pin.
			I/O	-	SSEL0 — Slave Select for SPI0.
			I	-	CT16B0_CAP0 — Capture input 0 for 16-bit timer 0.
PIO0_4/SCL	20 [4]	yes	I/O	I; IA	PIO0_4 — General purpose digital input/output pin (open-drain).
			I/O	-	SCL — I ² C-bus, open-drain clock input/output. High-current sink only if I ² C Fast-mode Plus is selected in the I/O configuration register.
PIO0_5/SDA	5 [4]	yes	I/O	I; IA	PIO0_5 — General purpose digital input/output pin (open-drain).
			I/O	-	SDA — I ² C-bus, open-drain data input/output. High-current sink only if I ² C Fast-mode Plus is selected in the I/O configuration register.
PIO0_6/SCK0	6 [3]	yes	I/O	I; PU	PIO0_6 — General purpose digital input/output pin.
			I/O	-	SCK0 — Serial clock for SPI0.
PIO0_8/MISO0/ CT16B0_MAT0	1 [3]	yes	I/O	I; PU	PIO0_8 — General purpose digital input/output pin.
			I/O	-	MISO0 — Master In Slave Out for SPI0.
			O	-	CT16B0_MAT0 — Match output 0 for 16-bit timer 0.
PIO0_9/MOSI0/ CT16B0_MAT1	2 [3]	yes	I/O	I; PU	PIO0_9 — General purpose digital input/output pin.
			I/O	-	MOSI0 — Master Out Slave In for SPI0.
			O	-	CT16B0_MAT1 — Match output 1 for 16-bit timer 0.
SWCLK/PIO0_10/ SCK0/ CT16B0_MAT2	3 [3]	yes	I	I; PU	SWCLK — Serial wire clock.
			I/O	-	PIO0_10 — General purpose digital input/output pin.
			I/O	-	SCK0 — Serial clock for SPI0.
			O	-	CT16B0_MAT2 — Match output 2 for 16-bit timer 0.

Table 6. LPC1100L series: LPC1112 (HVQFN24 package) ...continued

Symbol	HVQFN pin	Start logic input	Type	Reset state [1]	Description
PIO0_5/SDA	9 ^[4]	yes	I/O	I; IA	PIO0_5 — General purpose digital input/output pin (open-drain).
			I/O	-	SDA — I ² C-bus, open-drain data input/output. High-current sink only if I ² C Fast-mode Plus is selected in the I/O configuration register.
PIO0_6/SCK0	10 ^[3]	yes	I/O	I; PU	PIO0_6 — General purpose digital input/output pin.
			I/O	-	SCK0 — Serial clock for SPI0.
PIO0_7/CTS	11 ^[3]	yes	I/O	I; PU	PIO0_7 — General purpose digital input/output pin (high-current output driver).
			I	-	CTS — Clear To Send input for UART.
PIO0_8/MISO0/ CT16B0_MAT0	12 ^[3]	yes	I/O	I; PU	PIO0_8 — General purpose digital input/output pin.
			I/O	-	MISO0 — Master In Slave Out for SPI0.
			O	-	CT16B0_MAT0 — Match output 0 for 16-bit timer 0.
PIO0_9/MOSI0/ CT16B0_MAT1	13 ^[3]	yes	I/O	I; PU	PIO0_9 — General purpose digital input/output pin.
			I/O	-	MOSI0 — Master Out Slave In for SPI0.
			O	-	CT16B0_MAT1 — Match output 1 for 16-bit timer 0.
SWCLK/PIO0_10/ SCK0/ CT16B0_MAT2	14 ^[3]	yes	I	I; PU	SWCLK — Serial wire clock.
			I/O	-	PIO0_10 — General purpose digital input/output pin.
			I/O	-	SCK0 — Serial clock for SPI0.
			O	-	CT16B0_MAT2 — Match output 2 for 16-bit timer 0.
R/PIO0_11/ AD0/CT32B0_MAT3	15 ^[5]	yes	I	I; PU	R — Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	PIO0_11 — General purpose digital input/output pin.
			I	-	AD0 — A/D converter, input 0.
			O	-	CT32B0_MAT3 — Match output 3 for 32-bit timer 0.
R/PIO1_0/ AD1/CT32B1_CAP0	16 ^[5]	yes	I	I; PU	R — Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	PIO1_0 — General purpose digital input/output pin.
			I	-	AD1 — A/D converter, input 1.
			I	-	CT32B1_CAP0 — Capture input 0 for 32-bit timer 1.
R/PIO1_1/ AD2/CT32B1_MAT0	17 ^[5]	no	O	I; PU	R — Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	PIO1_1 — General purpose digital input/output pin.
			I	-	AD2 — A/D converter, input 2.
			O	-	CT32B1_MAT0 — Match output 0 for 32-bit timer 1.
R/PIO1_2/ AD3/CT32B1_MAT1	18 ^[5]	no	I	I; PU	R — Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	PIO1_2 — General purpose digital input/output pin.
			I	-	AD3 — A/D converter, input 3.
			O	-	CT32B1_MAT1 — Match output 1 for 32-bit timer 1.

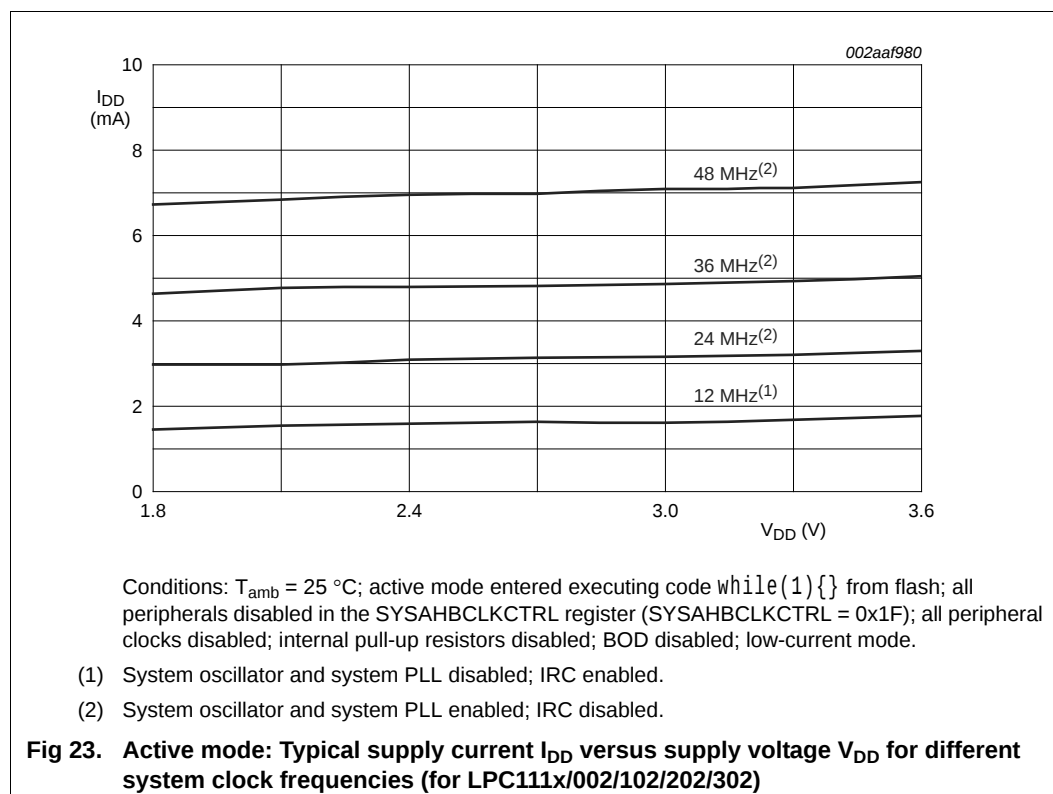
Table 11. LPC1100XL series: LPC1111/12/13/14 pin description table (HVQFN33 package) ...continued

Symbol	Pin	Start logic input	Type	Reset state [1]	Description
PIO1_7/TXD/ CT32B0_MAT1	32 ^[3]	no	I/O	I;PU	PIO1_7 — General purpose digital input/output pin.
			O	-	TXD — Transmitter output for UART.
			O	-	CT32B0_MAT1 — Match output 1 for 32-bit timer 0.
PIO1_8/ CT16B1_CAP0	7 ^[3]	no	I/O	I;PU	PIO1_8 — General purpose digital input/output pin.
			I	-	CT16B1_CAP0 — Capture input 0 for 16-bit timer 1.
PIO1_9/ CT16B1_MAT0/ MOSI1	12 ^[3]	no	I/O	I;PU	PIO1_9 — General purpose digital input/output pin.
			O	-	CT16B1_MAT0 — Match output 0 for 16-bit timer 1.
			I/O	-	MOSI1 — Master Out Slave In for SPI1
PIO1_10/AD6/ CT16B1_MAT1/ MISO1	20 ^[5]	no	I/O	I;PU	PIO1_10 — General purpose digital input/output pin.
			I	-	AD6 — A/D converter, input 6.
			O	-	CT16B1_MAT1 — Match output 1 for 16-bit timer 1.
			I/O	-	MISO1 — Master In Slave Out for SPI1
PIO1_11/AD7/ CT32B1_CAP1	27 ^[5]	no	I/O	I;PU	PIO1_11 — General purpose digital input/output pin.
			I	-	AD7 — A/D converter, input 7.
			I	-	CT32B1_CAP1 — Capture input 1 for 32-bit timer 1.
PIO2_0					Port 2 — Port 2 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 2 pins depends on the function selected through the IOCONFIG register block. Pins PIO2_1 to PIO2_11 are not available.
PIO2_0/DTR/SSEL1	1 ^[3]	no	I/O	I;PU	PIO2_0 — General purpose digital input/output pin.
			O	-	DTR — Data Terminal Ready output for UART.
			I/O	-	SSEL1 — Slave Select for SPI1.
PIO3_0 to PIO3_5					Port 3 — Port 3 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 3 pins depends on the function selected through the IOCONFIG register block. Pins PIO3_0, PIO3_1, PIO3_3 and PIO3_6 to PIO3_11 are not available.
PIO3_2/ CT16B0_MAT2/ SCK1	28 ^[3]	no	I/O	I;PU	PIO3_2 — General purpose digital input/output pin.
			O	-	CT16B0_MAT2 — Match output 2 for 16-bit timer 0.
			I/O	-	SCK1 — Serial clock for SPI1.
PIO3_4/ CT16B0_CAP1/RXD	13 ^[3]	no	I/O	I;PU	PIO3_4 — General purpose digital input/output pin.
			I	-	CT16B0_CAP1 — Capture input 1 for 16-bit timer 0.
			I	-	RXD — Receiver input for UART.
PIO3_5/ CT16B1_CAP1/TXD	14 ^[3]	no	I/O	I;PU	PIO3_5 — General purpose digital input/output pin.
			I	-	CT16B1_CAP1 — Capture input 1 for 16-bit timer 1.
			O	-	TXD — Transmitter output for UART.

10.6 Power consumption LPC1100L series (LPC111x/002/102/202/302)

Power measurements in Active, Sleep, and Deep-sleep modes were performed under the following conditions (see *LPC111x user manual*):

- Configure all pins as GPIO with pull-up resistor disabled in the IOCONFIG block.
- Configure GPIO pins as outputs using the GPIODIR registers.
- Write 0 to all GPIODATA registers to drive the outputs LOW.



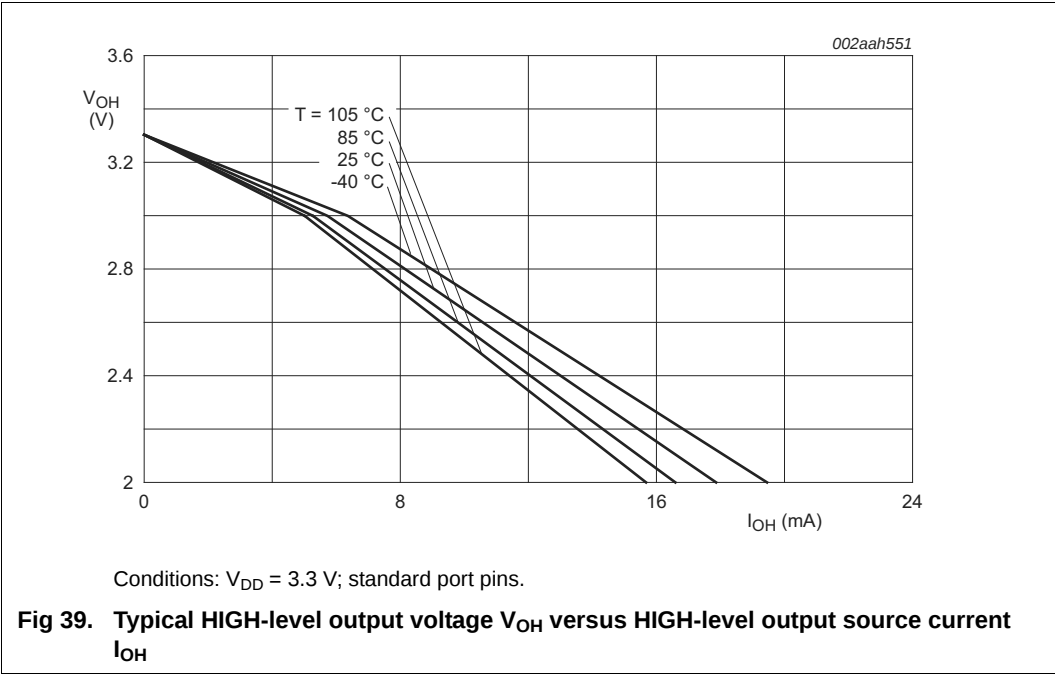
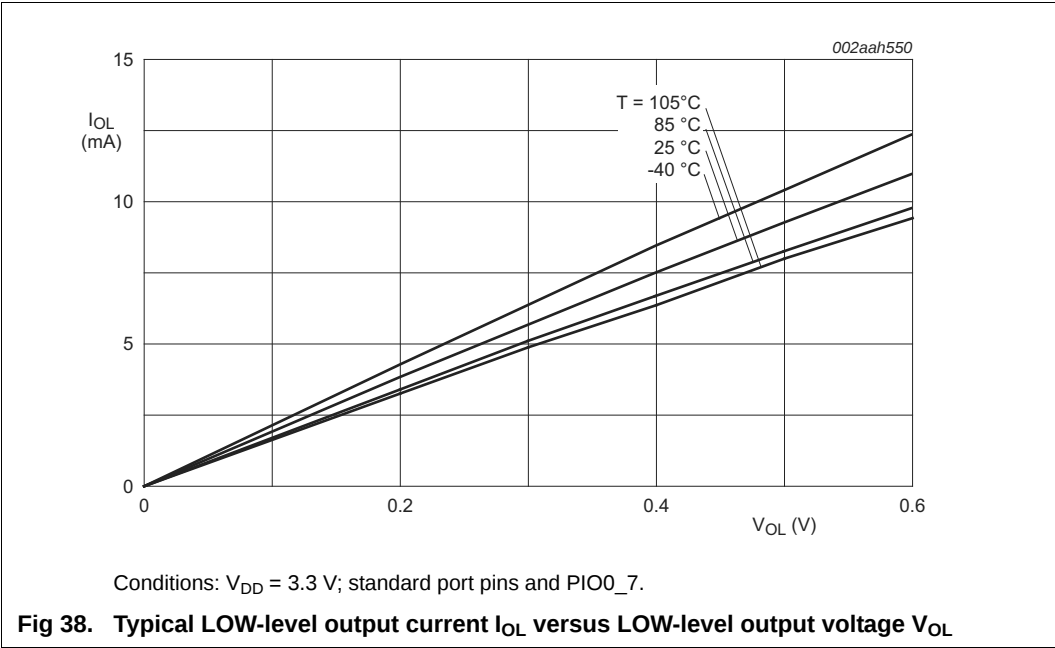


Table 26. Dynamic characteristics: Watchdog oscillator

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
$f_{\text{osc(int)}}$	internal oscillator frequency	DIVSEL = 0x1F, FREQSEL = 0x1 ^{[2][3]} in the WDTOSCCTRL register;	-	9.4	-	kHz
		DIVSEL = 0x00, FREQSEL = 0xF ^{[2][3]} in the WDTOSCCTRL register	-	2300	-	kHz

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

[2] The typical frequency spread over processing and temperature ($T_{\text{amb}} = -40\text{ °C}$ to $+105\text{ °C}$) is $\pm 40\%$.

[3] See the LPC111x user manual.

11.5 I/O pins

Table 27. Dynamic characteristic: I/O pins^[1]

$T_{\text{amb}} = -40\text{ °C}$ to $+105\text{ °C}$; $3.0\text{ V} \leq V_{\text{DD}} \leq 3.6\text{ V}$.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_r	rise time	pin configured as output	3.0	-	5.0	ns
t_f	fall time	pin configured as output	2.5	-	5.0	ns

[1] Applies to standard port pins and $\overline{\text{RESET}}$ pin.

12. Application information

12.1 ADC usage notes

The following guidelines show how to increase the performance of the ADC in a noisy environment beyond the ADC specifications listed in [Table 18](#):

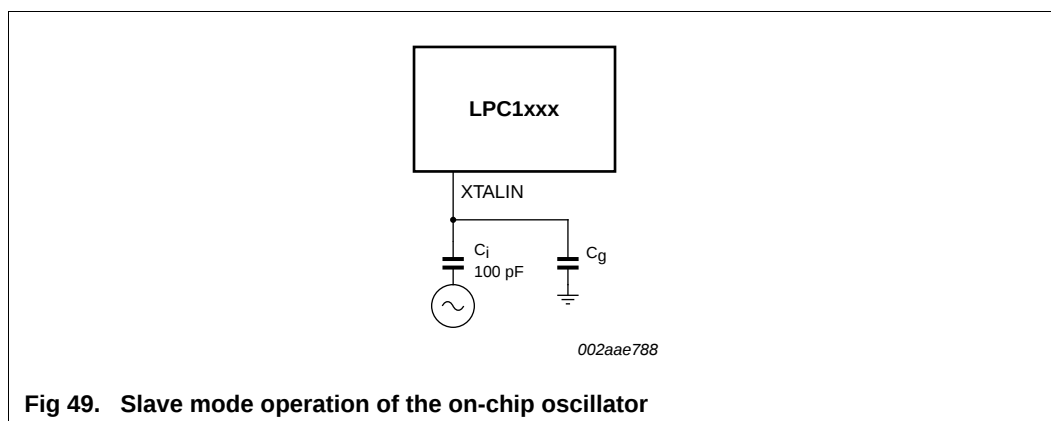
- The ADC input trace must be short and as close as possible to the LPC1110/11/12/13/14/15 chip.
- The ADC input traces must be shielded from fast switching digital signals and noisy power supply lines.
- Because the ADC and the digital core share the same power supply, the power supply line must be adequately filtered.
- To improve the ADC performance in a very noisy environment, put the device in Sleep mode during the ADC conversion.

12.2 Use of ADC input trigger signals

For applications that use trigger signals to start conversions and require a precise sample frequency, ensure that the period of the trigger signal is an integral multiple of the period of the ADC clock.

12.3 XTAL input

The input voltage to the on-chip oscillators is limited to 1.8 V. If the oscillator is driven by a clock in slave mode, it is recommended that the input be coupled through a capacitor with $C_i = 100$ pF. To limit the input voltage to the specified range, choose an additional capacitor to ground C_g which attenuates the input voltage by a factor $C_i/(C_i + C_g)$. In slave mode, a minimum of 200 mV (RMS) is needed.



In slave mode the input clock signal should be coupled by means of a capacitor of 100 pF ([Figure 49](#)), with an amplitude between 200 mV (RMS) and 1000 mV (RMS). This corresponds to a square wave signal with a signal swing of between 280 mV and 1.4 V. The XTALOUT pin in this configuration can be left unconnected.

External components and models used in oscillation mode are shown in [Figure 50](#) and in [Table 30](#) and [Table 31](#). Since the feedback resistance is integrated on chip, only a crystal and the capacitances C_{X1} and C_{X2} need to be connected externally in case of

12.4 XTAL Printed Circuit Board (PCB) layout guidelines

The crystal should be connected on the PCB as close as possible to the oscillator input and output pins of the chip. Take care that the load capacitors C_{X1} , C_{X2} , and C_{X3} in case of third overtone crystal usage have a common ground plane. The external components must also be connected to the ground plain. Loops must be made as small as possible in order to keep the noise coupled in via the PCB as small as possible. Also parasitics should stay as small as possible. Values of C_{X1} and C_{X2} should be chosen smaller accordingly to the increase in parasitics of the PCB layout.

12.5 Standard I/O pad configuration

Figure 51 shows the possible pin modes for standard I/O pins with analog input function:

- Digital output driver
- Digital input: Pull-up enabled/disabled
- Digital input: Pull-down enabled/disabled
- Digital input: Repeater mode enabled/disabled
- Digital output: Pseudo open-drain mode enable/disabled
- Analog input

12.7 ElectroMagnetic Compatibility (EMC)

Radiated emission measurements according to the IEC61967-2 standard using the TEM-cell method are shown for the LPC1114FBD48/302 in [Table 32](#).

Table 32. ElectroMagnetic Compatibility (EMC) for part LPC1114FBD48/302 (TEM-cell method)

$V_{DD} = 3.3\text{ V}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$.

Parameter	Frequency band	System clock =			Unit
		12 MHz	24 MHz	48 MHz	
Input clock: IRC (12 MHz)					
maximum peak level	150 kHz to 30 MHz	−7	−5	−7	dBμV
	30 MHz to 150 MHz	−2	1	10	dBμV
	150 MHz to 1 GHz	4	8	16	dBμV
IEC level ^[1]	-	O	N	M	-
Input clock: crystal oscillator (12 MHz)					
maximum peak level	150 kHz to 30 MHz	−7	−7	−7	dBμV
	30 MHz to 150 MHz	−2	1	8	dBμV
	150 MHz to 1 GHz	4	7	14	dBμV
IEC level ^[1]	-	O	N	M	-

[1] IEC levels refer to Appendix D in the IEC61967-2 Specification.

12.8 ADC effective input impedance

A simplified diagram of the ADC input channels can be used to determine the effective input impedance seen from an external voltage source. See [Figure 53](#).

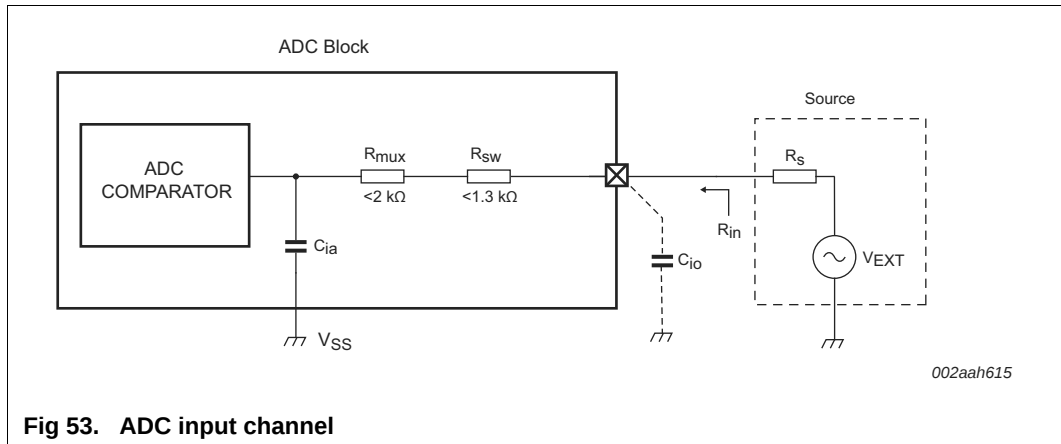


Fig 53. ADC input channel

The effective input impedance, R_{in} , seen by the external voltage source, V_{EXT} , is the parallel impedance of $((1/f_s \times C_{ia}) + R_{mux} + R_{sw})$ and $(1/f_s \times C_{io})$, and can be calculated using [Equation 2](#) with

f_s = sampling frequency

C_{ia} = ADC analog input capacitance

R_{mux} = analog mux resistance

R_{sw} = switch resistance

C_{io} = pin capacitance

$$R_{in} = \left(\frac{1}{f_s \times C_{ia}} + R_{mux} + R_{sw} \right) \parallel \left(\frac{1}{f_s \times C_{io}} \right) \quad (2)$$

Under nominal operating condition $V_{DD} = 3.3$ V and with the maximum sampling frequency $f_s = 400$ kHz, the parameters assume the following values:

$C_{ia} = 1$ pF (max)

$R_{mux} = 2$ k Ω (max)

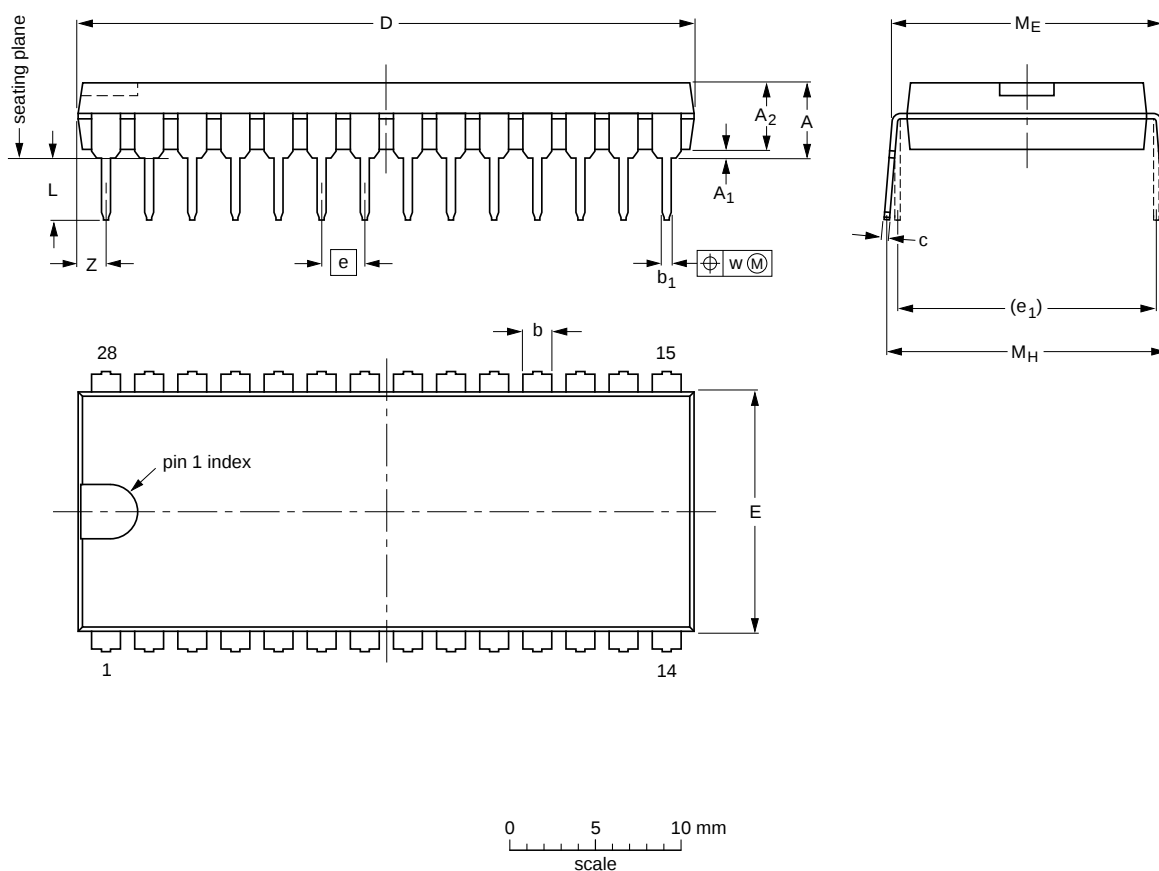
$R_{sw} = 1.3$ k Ω (max)

$C_{io} = 7.1$ pF (max)

The effective input impedance with these parameters is $R_{in} = 308$ k Ω .

DIP28: plastic dual in-line package; 28 leads (600 mil)

SOT117-1



DIMENSIONS (mm dimensions are derived from the original inch dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	5.1	0.51	4	1.7 1.3	0.53 0.38	0.32 0.23	36 35	14.1 13.7	2.54	15.24	3.9 3.4	15.80 15.24	17.15 15.90	0.25	1.7
inches	0.2	0.02	0.16	0.066 0.051	0.020 0.014	0.013 0.009	1.41 1.34	0.56 0.54	0.1	0.6	0.15 0.13	0.62 0.60	0.68 0.63	0.01	0.067

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT117-1	051G05	MO-015	SC-510-28			99-12-27 03-02-13

Fig 57. Package outline SOT117-1 (DIP28)

14. Soldering

